CHIPQUIK® AD1-10S

Datasheet revision 1.3 www.chipquik.com

Thermoset Chip Glue (Red) - 10cc syringe



Product Highlights

Heat curing epoxy adhesive designed to bond surface mount chips and ICs to printed circuit boards (PCBs). Higher Viscosity for Stencil Printing. Designed to be printed with stencil and squeegee.

Allows large/heavy surface mount components to be permanently bonded to a PCB during reflow, allowing two-sided surface mount reflow without larger chips/ICs coming loose.

Specifications

Curing Time:	90 to 120 seconds at 150+ °C (302+ °F)
Recommended Curing Temperature:	150 to 260 °C (302 to 500 °F)
Maximum Curing Temperature:	260 °C (500 °F) Designed to cure at leaded and lead free reflow temperatures.
Operating Temperature Range:	-40 to 125 °C (-40 to 257 °F) (After Curing, After Reflow)
Lap Shear Strength (After Curing):	>15MPa (Steel-Steel, 25 °C (77 °F))
Packaging:	10cc/10g Syringe
Shelf Life:	Refrigerated >12 months, Unrefrigerated >12 months

Stencil Life

>8 hours @ 20-50% RH 22-28°C (72-82°F), >4 hours @ 50-70% RH 22-28°C (72-82°F)

Application

Apply by dot dispensing, line dispensing, or with stencil and squeegee.

Cleaning

Clean using isopropyl alcohol (IPA).

Storage and Handling

Store at 3-25°C (37-77°F). Do not freeze. Allow 4 hours for thermoset chip glue to reach an operating temperature of 20-25°C (68-77°F) before use.

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

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